

DESCRIPTION

The SPN7002L is the N-Channel enhancement mode field effect transistors are produced using high cell density DMOS technology. These products have been designed to minimize on-state resistance while provide rugged, reliable, and fast switching performance. They can be used in most applications requiring up to 300mA DC and can deliver pulsed currents up to 0.8A. These products are particularly suited for low voltage, low current applications such as small servo motor control, power MOSFET gate drivers, and other switching applications.

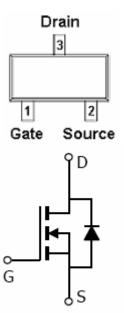
APPLICATIONS

- Drivers: Relays, Solenoids, Lamps, Hammers, Display, Memories, Transistors, etc.
- High saturation current capability. Direct Logic-Level Interface: TTL/CMOS
- Battery Operated Systems
- Solid-State Relays

FEATURES

- 50V/0.30A, RDS(ON)= 3.5Ω @VGS=10V
- 50V/0.25A, RDS(ON)= $5.5\Omega@VGS=4.5V$
- 50V/0.05A, RDS(ON)= 7.5Ω @VGS=2.5V
- ◆ Super high density cell design for extremely low RDS (ON)
- Exceptional on-resistance and maximum DC current capability
- ♦ SOT-23 package design

PIN CONFIGURATION(SOT-23)



PART MARKING



Y : Year Code W : Week Code

PIN DESCRIPTION

Pin	Symbol	Description
1	G	Gate
2	S	Source
3	D	Drain

ORDERING INFORMATION

Part Number	Package	Part Marking
SPN7002LS23RG	SOT-23	L72YW

% Week Code : $A \sim Z(1 \sim 26)$; $a \sim z(27 \sim 52)$ % SPN7002LS23RG : Tape Reel ; Pb – Free

ABSOULTE MAXIMUM RATINGS (TA=25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit	
Drain-Source Voltage	Vdss	50	V	
Gate –Source Voltage - Continuous		VGSS	±20	V
Gate –Source Voltage - Non Repetitive (t _p < 50μs)		VGSS	±40	V
Continuous Drain Current(TJ=150°€)	Ta=25°C	ID	ID 0.3	
Pulsed Drain Current (*)		Ірм	0.8	A
Power Dissipation	Ta=25°C	PD	0.35	W
Operating Junction Temperature		Тл	- 55 ∼ 150	$^{\circ}\!\mathbb{C}$
Storage Temperature Range		Tstg	- 55 ∼ 150	°C
Thermal Resistance-Junction to Ambient		RθJA	375	°C/W

(*) Pulse width limited by safe operating area

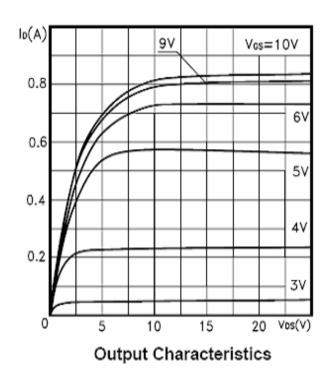
ELECTRICAL CHARACTERISTICS (TA=25°C Unless otherwise noted)

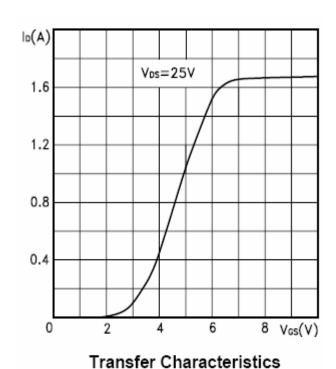
Parameter	Symbol	Conditions	Min.	Тур	Max.	Unit	
Static	L						
Drain-Source Breakdown Voltage	V(BR)DSS	V _G S=0V,I _D =250uA	50			V	
Gate Threshold Voltage	VGS(th)	VDS=VGS,ID=250uA	0.8	1.25	1.5	\ \	
Gate Leakage Current	Igss	V _{DS} =0V,V _{GS} =±20V			±100	nA	
		V _{DS} =45V,V _{GS} =0V			1	1 10 uA	
Zero Gate Voltage Drain Current	IDSS	VDS=45V,VGS=0V TJ=125°C			10		
		Vgs=10V,Id=0.30A		2.5	3.5	Ω	
Drain-Source On-Resistance	RDS(on)	V _{GS} = 4.5V,I _D =0.25A		3.3	5.5		
		V _{GS} = 2.5V,I _D =0.05A		5.0	7.5		
Source-drain Current	ISD Ispan(2)				0.35	A	
Source-drain Current (pulsed) Forward Transconductance	ISDM (2) Gfs(1)	$V_{DS} = 10 \text{ V}, I_{D} = 0.5 \text{ A}$		0.6	1.4	A S	
Diode Forward Voltage	VsD(1)	$V_{GS} = 0 \text{ V}, \text{ Is} = 0.12 \text{A}$		0.85	1.5	V	
Dynamic					l		
Total Gate Charge	Qg			1.4	2.0		
Gate-Source Charge	Qgs	$V_{DD} = 30 \text{ V}, I_{D} = 1 \text{ A}, V_{GS} = 5 \text{ V}$		0.8		nC	
Gate-Drain Charge	Qgd	V GS — 3 V		0.5			
Input Capacitance	Ciss			43		pF	
Output Capacitance	Coss	$V_{DS} = 25 \text{ V, } f = 1 \text{ MHz,}$ $V_{GS} = 0$		20			
Reverse Transfer Capacitance	Crss	V G 5 V		6] 	
T. O. T.	td(on)			5		- ns	
Turn-On Time	tr	$V_{DD} = 30 \text{ V}, I_{D} = 0.5 \text{ A}$		15			
T Off Time	td(off)	$R_G = 4.7\Omega \text{ V}_{GS} = 4.5 \text{ V}$		7			
Turn-Off Time	tf			8			

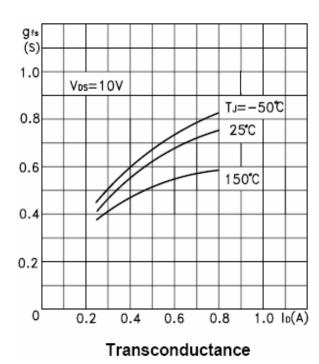
⁽¹⁾ Pulsed: Pulse duration = 300 μ s, duty cycle 1.5 %.

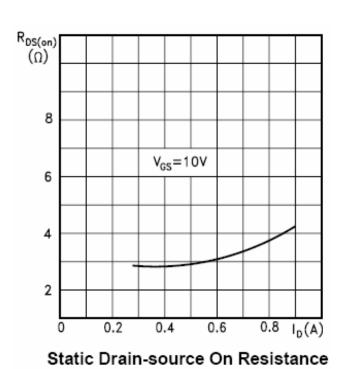
⁽²⁾ Pulse width limited by safe operating area.

TYPICAL CHARACTERISTICS

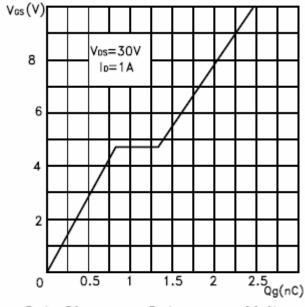






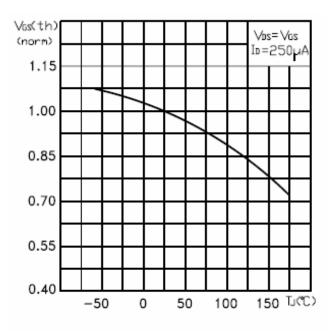


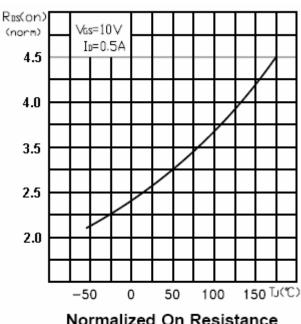
TYPICAL CHARACTERISTICS



Gate Charge vs Gate-source Voltage







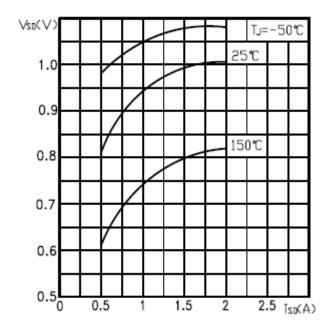
Normalized Gate Threshold Voltage vs Temperature

Normalized On Resistance vs Temperature

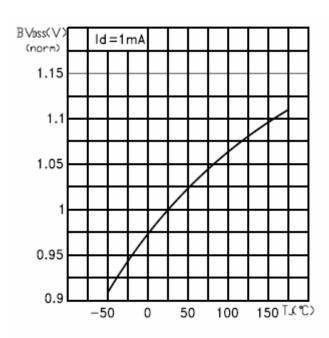


N-Channel Enhancement Mode MOSFET

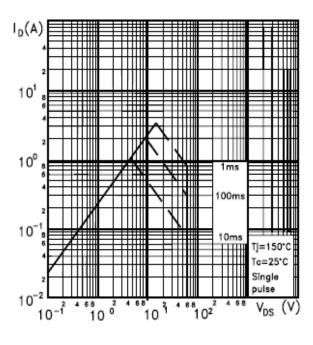
TYPICAL CHARACTERISTICS



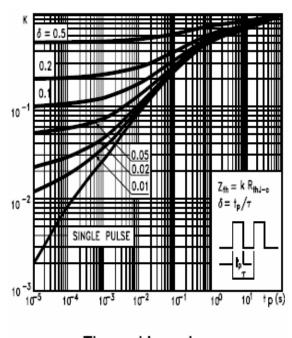
Source-Drain Forward



Normalized BVDSS vs Temperature

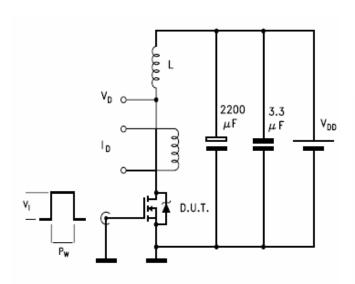


Safe Operating Area

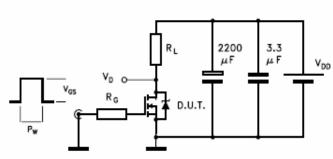


Thermal Impedance

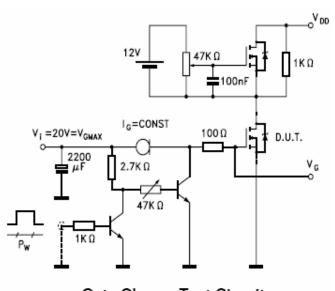
TYPICAL TESTING CIRCUIT



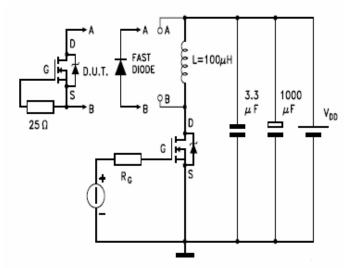
Unclamped Inductive Load Test



Switching Times Test Circuit



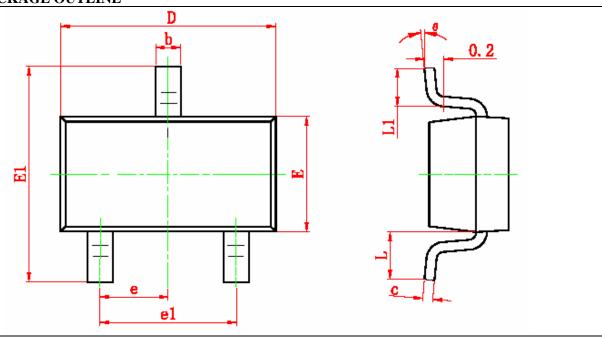
Gate Charge Test Circuit

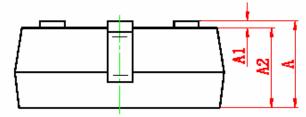


Test Circuit For Inductive Load Switching and Diode Recovery Times



SOT-23 PACKAGE OUTLINE





Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
Α	0.900	1.200	0.035	0.043	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.100	0.035	0.039	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP		0.037 TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	6°	

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SYNC Power Corporation
9F-5, No.3-2, Park Street
NanKang District (NKSP), Taiwan, 115, R.O.C
Phone: 886-2-2655-8178

Fax: 886-2-2655-8468 ©http://www.syncpower.com